

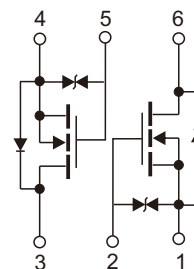
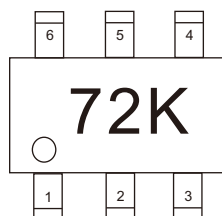
Features

- High density cell design for low RDS(ON)
- Rugged and reliable
- High saturation current capability
- Voltage controlled small signal switch
- Low input Capacitance
- Fast Switching Speed



| Product Summary | | |
|-----------------|-----------------------------|---------------------|
| V _{DS} | R _{DS(on)} (Ω) Typ | I _D (mA) |
| 60V | 1.1@ 4.5V 0.2A | 340 |
| | 0.9@ 10V 0.5A | |

SOT-363



N-channel MOSFET

Mechanical Data

- Case:SOT-363
- Terminals:Plated solderable per MIL-STD-750,method 2026
- Mounting Position: Any
- Marking:72K

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

| Parameters | Symbol | Value | Unit |
|---|-----------------------------------|-------------|------|
| Drain-Source voltage | V _{DS} | 60 | V |
| Gate-Source Voltage | V _{GS} | ±20 | V |
| Continuous Drain Current | I _D | 340 | mA |
| Pulsed Drain Current ¹⁾ | I _{DM} | 1.5 | A |
| Maximum Power Dissipation @T _A =25°C | P _D | 150 | mW |
| Junction and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Thermal Resistance Ratings

| Parameters | Symbol | Typ | Max | Unit |
|---|------------------|-----|-----|------|
| Junction to Ambient, Steady State ²⁾ | R _{θJA} | - | 833 | °C/W |

Electrical Characteristics (T_J=25°C unless otherwise noted)

| Parameters | Symbol | Conditions | Min | Typ | Max | Unit |
|---|---------------------|--|-----|------|-----|------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} = 0V, I _D =250μA | 60 | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =60V, V _{GS} =0V, T _C =25°C | - | - | 1 | μA |
| Gate-Source Leakage Current | I _{GSS} | V _{GS} = ±20V, V _{DS} =0V | - | - | ±10 | μA |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D =250μA | 1.0 | 1.3 | 2.5 | V |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10V, I _D =500mA | - | 0.9 | 5.0 | Ω |
| | | V _{GS} = 4.5V, I _D =200mA | - | 1.1 | 5.3 | |
| Dynamic | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =10V, V _{GS} =0V, f=1MHz | - | - | 40 | pF |
| Output Capacitance | C _{oss} | | - | - | 30 | |
| Reverse Transfer Capacitance | C _{rss} | | - | - | 10 | |
| Total Gate Charge | Q _g | V _{DS} =30V, V _{GS} =10V, I _D =0.3A | - | 1.65 | - | nC |
| Gate-Source Charge | Q _{GS} | | - | 10.4 | - | |
| Gate-Drain Charge | Q _{GD} | | - | 0.24 | - | |
| Turn-on Delay Time | t _{D(on)} | V _{GS} =10V, V _{DD} =50V, R _{GEN} =50Ω, I _D =0.34A | - | - | 10 | ns |
| Turn-off Delay Time | t _{D(off)} | | - | - | 15 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Maximum Body-Diode Continuous Current | I _S | | - | - | 300 | mA |
| Diode Forward Voltage | V _{SD} | I _S =0.3mA, V _{GS} =0V | | | 1.2 | V |
| Reverse recovery Time | t _{rr} | V _{GS} =0V, V _R =25V, di/dt=100A/μs, I _S =0.3A | - | 30 | - | ns |

Notes: 1. Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.
2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Characteristics Diagrams

Figure 1. Output Characteristics

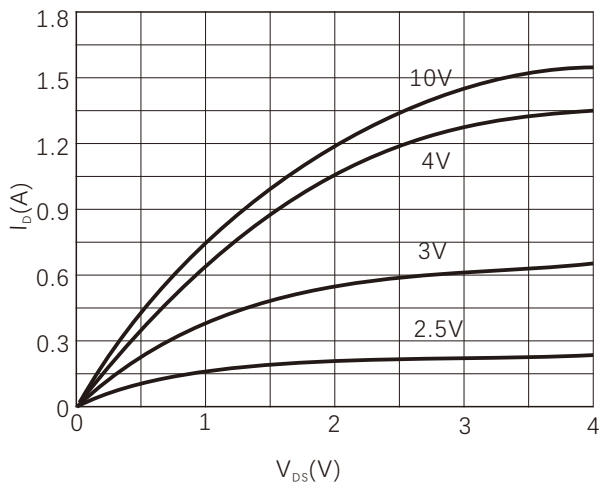


Figure 2. Transfer Characteristics

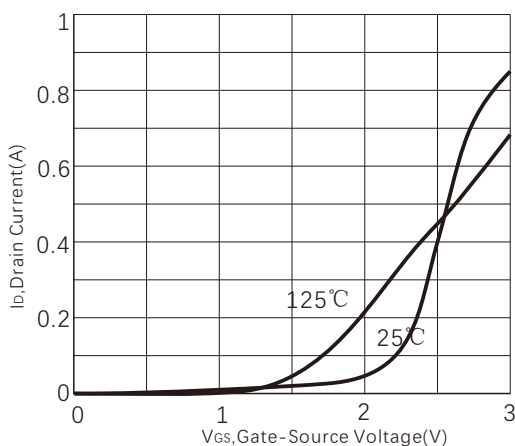


Figure 3. On-Resistance vs. Drain Current

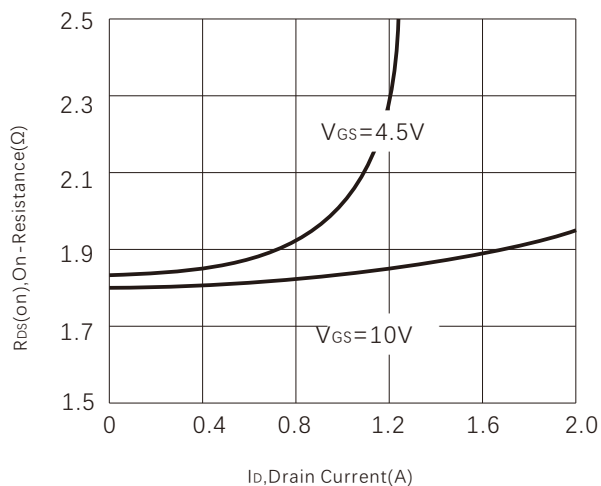
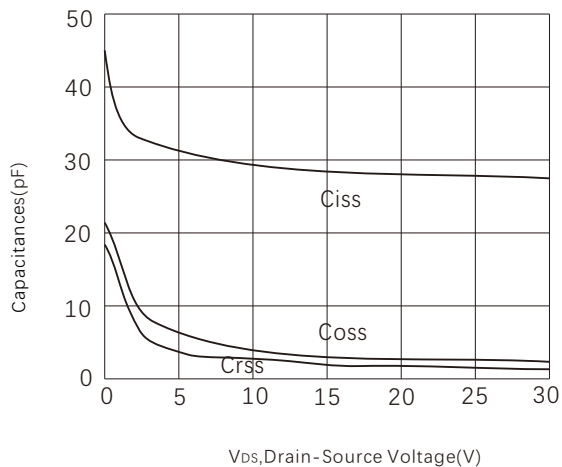


Figure 4. Capacitance



Typical Characteristics Diagrams

Figure 5. Gate charge

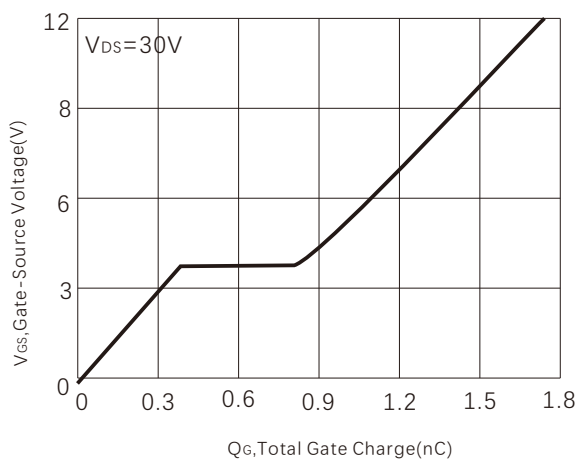


Figure 6. Normalized $R_{DS(ON)}$ vs Junction Temperature

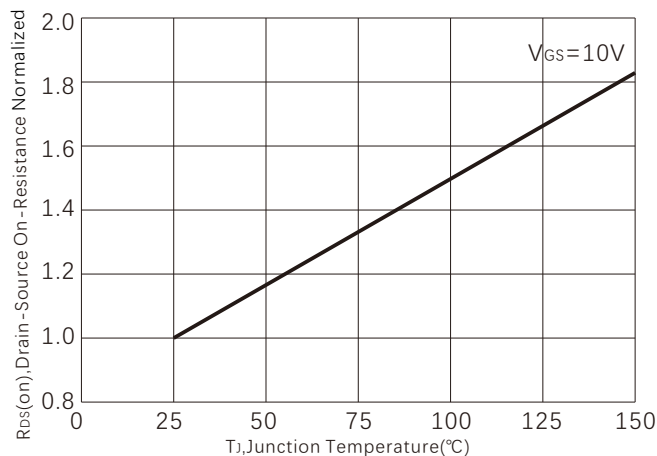


Figure 7. Safe operating area

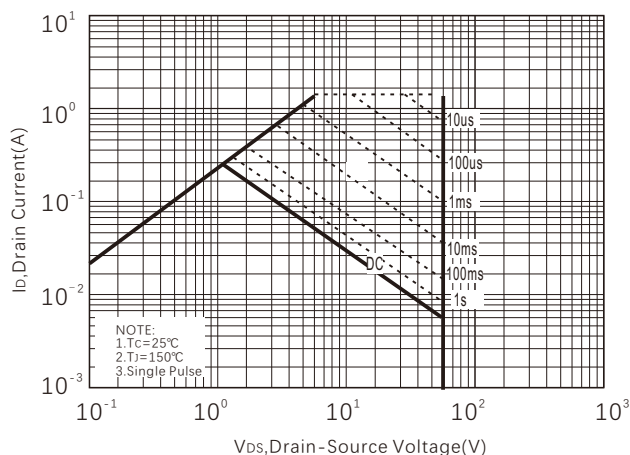
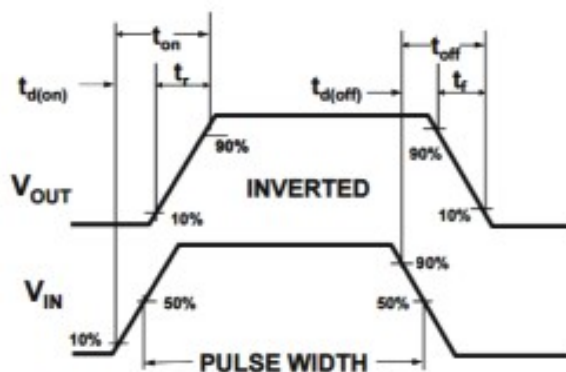
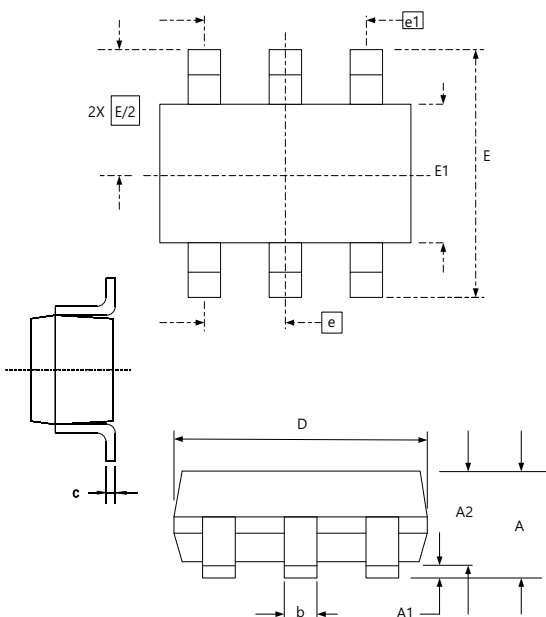


Figure 8. Switching wave



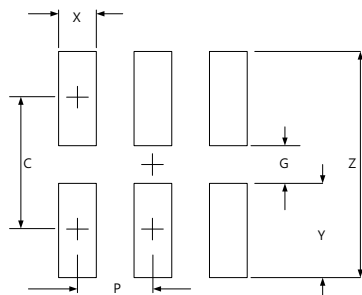
PACKAGE OUTLINE DIMENSIONS

SOT-363



| SYM | DIMENSIONS | | | | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MILLIMETERS | | | INCHES | | |
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.90 | | 1.10 | 0.035 | | 0.043 |
| A1 | 0.00 | | 0.10 | 0.000 | | 0.004 |
| A2 | 0.70 | 0.90 | 1.00 | 0.028 | 0.035 | 0.039 |
| b | 0.15 | | 0.35 | 0.006 | | 0.014 |
| c | 0.08 | | 0.25 | 0.003 | | 0.010 |
| D | 1.80 | 2.00 | 2.20 | 0.071 | 0.079 | 0.087 |
| E1 | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 |
| E | 2.15 | 2.30 | 2.45 | 0.085 | 0.091 | 0.096 |
| e | 0.65 BSC | | | 0.026 BSC | | |
| e1 | 1.30 BSC | | | 0.051 BSC | | |

Suggested pad layout



| SYM | DIMENSIONS | |
|-----|-------------|--------|
| | MILLIMETERS | INCHES |
| C | 1.85 | 0.073 |
| G | 1.00 | 0.039 |
| P | 0.65 | 0.026 |
| X | 0.40 | 0.016 |
| Y | 0.85 | 0.033 |
| Z | 2.70 | 0.106 |

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